

2SK2933

Silicon N Channel MOS FET High Speed Power Switching

REJ03G1047-0400

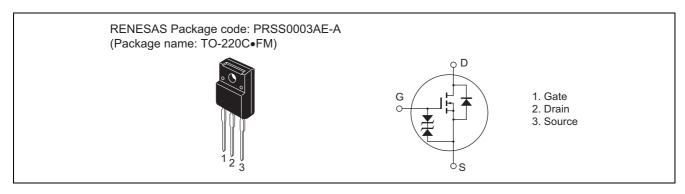
(Previous: ADE-208-556B)

Rev.4.00 Sep 07, 2005

Features

- Low on-resistance $R_{DS(on)} = 0.040 \; \Omega \; typ. \label{eq:DS_DS}$
- 4 V gate drive devices.
- High speed switching

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	60	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I _D	15	A
Drain peak current	I _{D(pulse)} Note1	60	Α
Body-drain diode reverse drain current	I _{DR}	15	А
Avalanche current	I _{AP} Note3	15	А
Avalanche energy	E _{AR} Note3	19	mJ
Channel dissipation	Pch Note2	25	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Ta = 25°C

3. Value at Tch = 25°C, Rg \geq 50 Ω

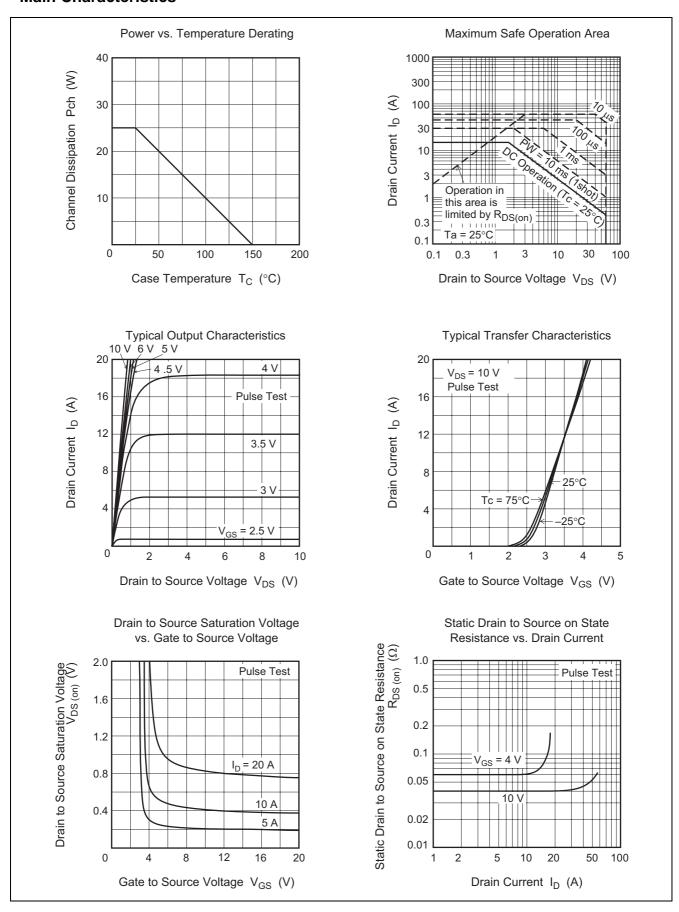
Electrical Characteristics

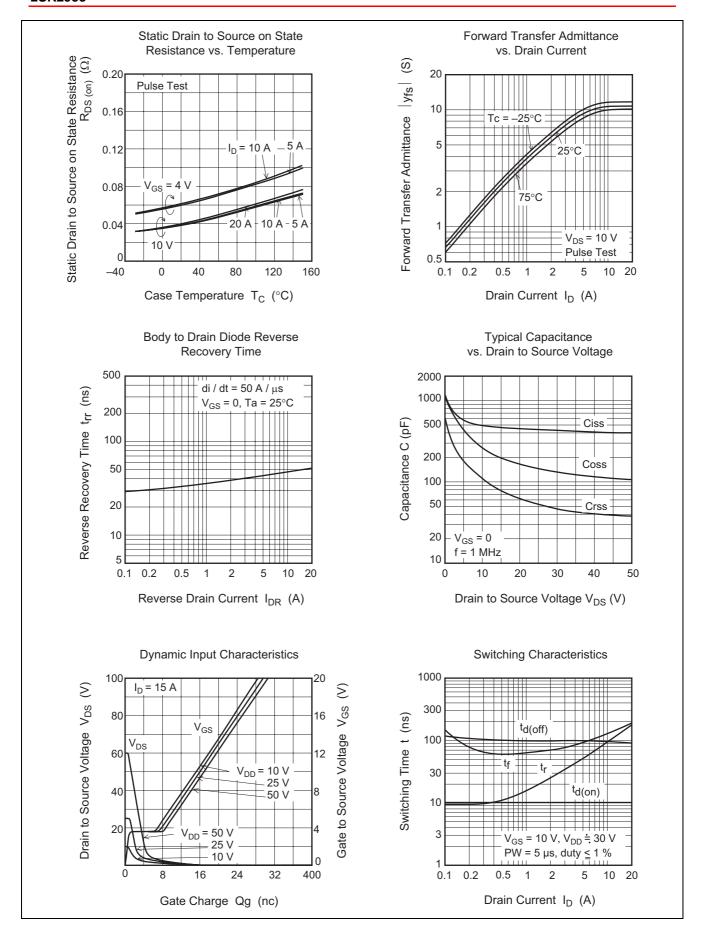
 $(Ta = 25^{\circ}C)$

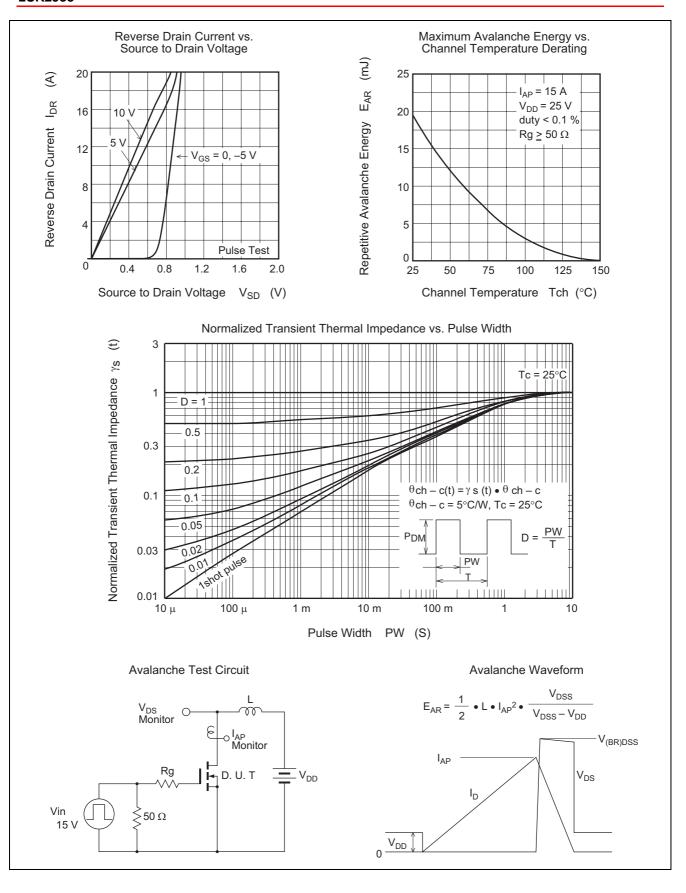
Item	Symbol	Min	Тур	Max	Unit	Test Conditions	
Drain to source breakdown voltage	V _{(BR)DSS}	60	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$	
Gate to source breakdown voltage	V _{(BR)GSS}	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$	
Zero gate voltage drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 60 \text{ V}, V_{GS} = 0$	
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$	
Gate to source cutoff voltage	V _{GS(off)}	1.5	_	2.5	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$	
Static drain to source on state	R _{DS(on)}	_	0.040	0.052	Ω	$I_D = 8 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note4}}$	
resistance	R _{DS(on)}	_	0.060	0.105	Ω	$I_D = 8 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note4}}$	
Forward transfer admittance	y _{fs}	7	11	_	S	$I_D = 8 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$	
Input capacitance	Ciss	_	500	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$ f = 1 MHz	
Output capacitance	Coss	_	260	_	pF		
Reverse transfer capacitance	Crss	_	110	_	pF		
Turn-on delay time	t _{d(on)}	_	10	_	ns	$V_{GS} = 10 \text{ V}, \text{ I}_D = 8 \text{ A},$ $R_L = 3.75 \Omega$	
Rise time	t _r	_	80	_	ns		
Turn-off delay time	t _{d(off)}	_	100	_	ns		
Fall time	t _f	_	110	_	ns]	
Body-drain diode forward voltage	V_{DF}	_	0.9	_	V	I _F = 15 A, V _{GS} = 0	
Body-drain diode reverse	t _{rr}	_	50	_	ns	I _F = 15 A, V _{GS} = 0	
recovery time						di _F / dt =50 A/ μs	

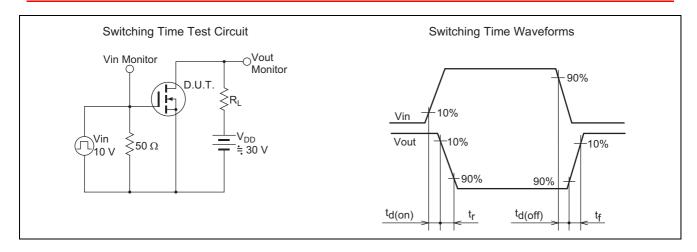
Note: 4. Pulse test

Main Characteristics

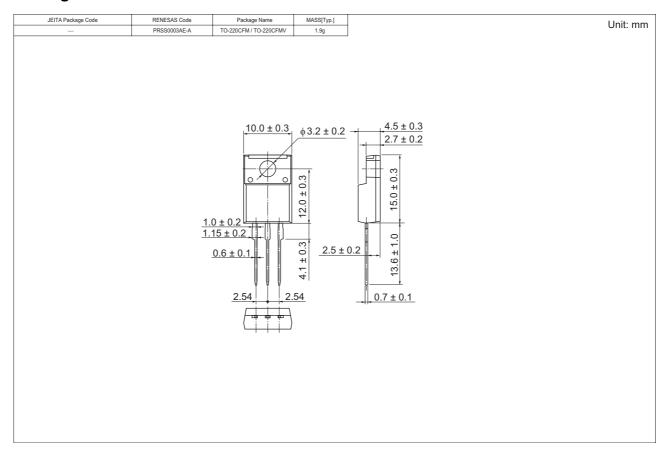








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK2933-E	600 pcs	Box (Tube)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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